

# FQB8N90C

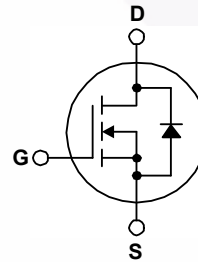
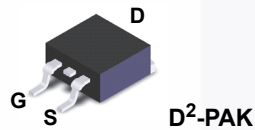
## N-Channel QFET® MOSFET 900 V, 6.3 A, 1.9 Ω

### Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies.

### Features

- 6.3 A, 900 V,  $R_{DS(on)} = 1.9 \Omega$  (Max.) @  $V_{GS} = 10 V$
- Low Gate Charge (Typ. 35 nC)
- Low  $C_{rss}$  (Typ. 12 pF)
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	FQB8N90CTM	Unit
$V_{DSS}$	Drain-Source Voltage	900	V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ ) - Continuous ( $T_C = 100^\circ\text{C}$ )	6.3	A
		3.8	A
$I_{DM}$	Drain Current - Pulsed (Note 1)	25	A
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	850	mJ
$I_{AR}$	Avalanche Current (Note 1)	6.3	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	17.1	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.0	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ ) - Derate Above $25^\circ\text{C}$	171	W
		1.37	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds.	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	FQB8N90CTM	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.73	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	

## Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQB8N90CTM	FQB8N90C	D <sup>2</sup> -PAK	Tape and Reel	330 mm	24 mm	800 units

## Electrical Characteristics

T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	900	--	--	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C	--	0.95	--	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 900 V, V <sub>GS</sub> = 0 V	--	--	10	μA
		V <sub>DS</sub> = 720 V, T <sub>C</sub> = 125°C	--	--	100	μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V	--	--	-100	nA

### On Characteristics

V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	--	5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.15 A	--	1.6	1.9	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 3.15 A	--	5.5	--	S

### Dynamic Characteristics

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz	--	1600	2080	pF
C <sub>oss</sub>	Output Capacitance		--	130	170	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	12	15	pF

### Switching Characteristics

t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 450 V, I <sub>D</sub> = 8 A, V <sub>GS</sub> = 10 V, R <sub>G</sub> = 25 Ω	--	40	90	ns	
t <sub>r</sub>	Turn-On Rise Time		--	110	230	ns	
t <sub>d(off)</sub>	Turn-Off Delay Time		(Note 4)	--	70	150	ns
t <sub>f</sub>	Turn-Off Fall Time		(Note 4)	--	70	150	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 720 V, I <sub>D</sub> = 8 A, V <sub>GS</sub> = 10 V	--	35	45	nC	
Q <sub>gs</sub>	Gate-Source Charge		(Note 4)	--	10	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		(Note 4)	--	14	--	nC

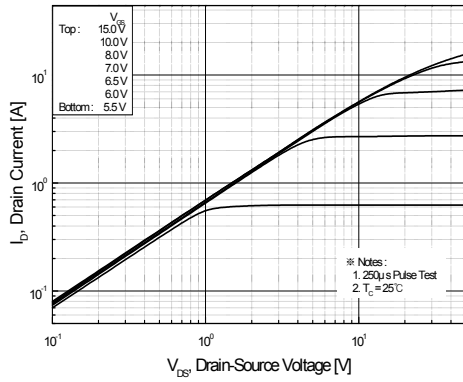
### Drain-Source Diode Characteristics and Maximum Ratings

I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current	--	--	6.3	A	
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current	--	--	25	A	
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 6.3 A	--	--	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 8 A, di <sub>F</sub> / dt = 100 A/μs	--	530	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	5.8	--	μC

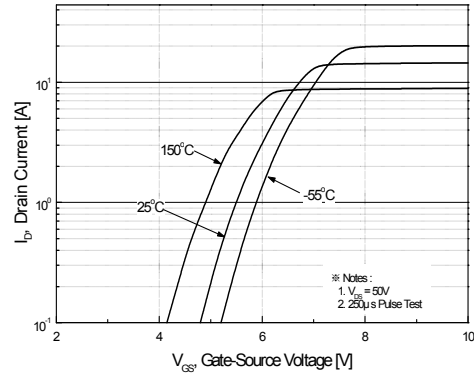
#### Notes:

1. Repetitive rating : pulse-width limited by maximum junction temperature.
2. L = 40 mH, I<sub>AS</sub> = 6.3 A, V<sub>DD</sub> = 50 V, R<sub>G</sub> = 25 Ω, starting T<sub>J</sub> = 25°C.
3. I<sub>SD</sub> ≤ 8 A, di/dt ≤ 200 A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, starting T<sub>J</sub> = 25°C.
4. Essentially independent of operating temperature.

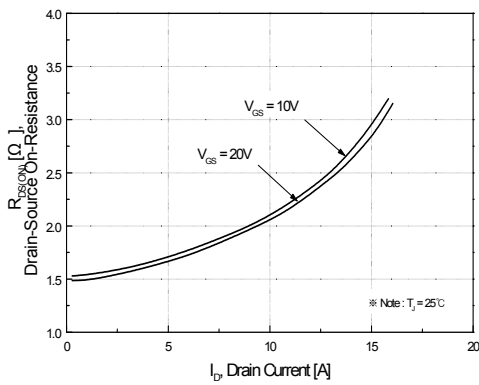
## Typical Characteristics



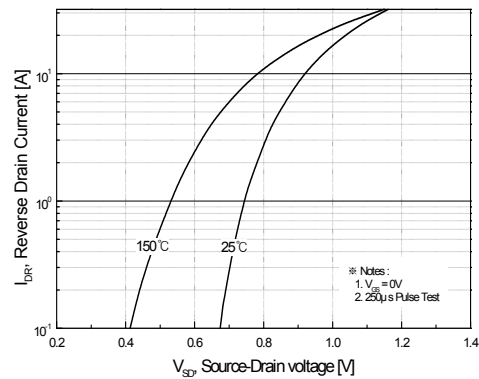
**Figure 1. On-Region Characteristics**



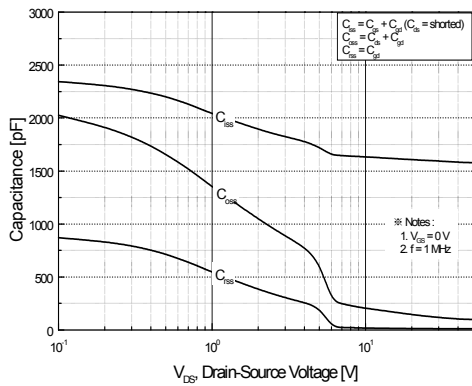
**Figure 2. Transfer Characteristics**



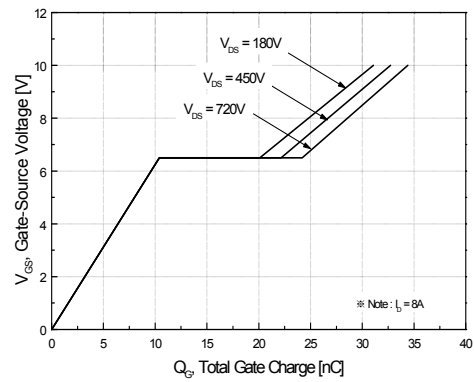
**Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

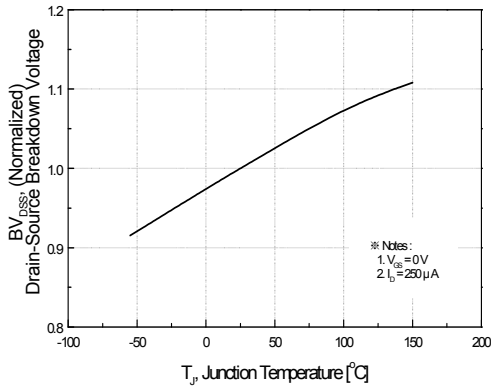


**Figure 5. Capacitance Characteristics**

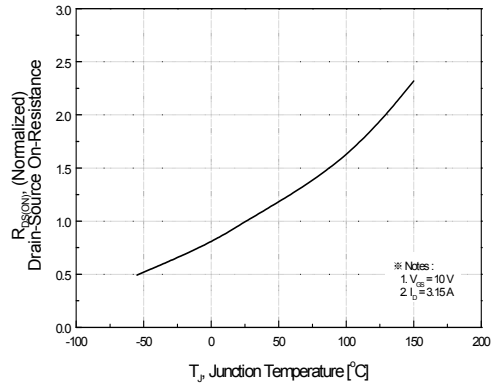


**Figure 6. Gate Charge Characteristics**

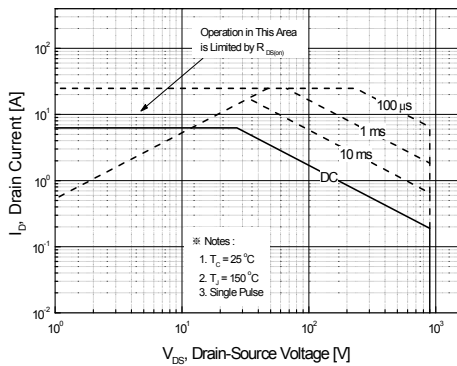
**Typical Characteristics** (Continued)



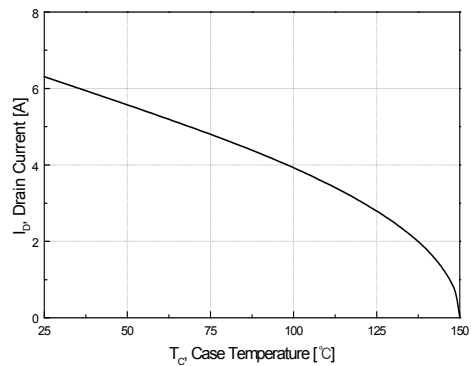
**Figure 7. Breakdown Voltage Variation vs Temperature**



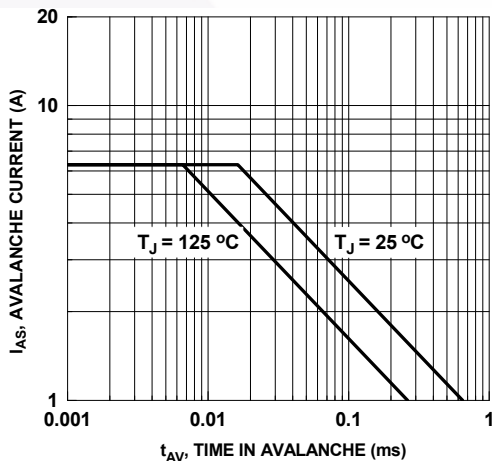
**Figure 8. On-Resistance Variation vs Temperature**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs Case Temperature**



**Figure 11. Unclamped Inductive Switching Capability**

Typical Characteristics (Continued)

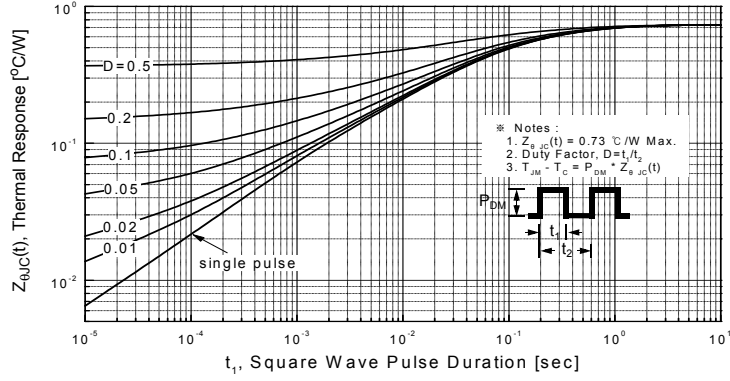


Figure 12. Transient Thermal Response Curve



Figure 13. Gate Charge Test Circuit & Waveform

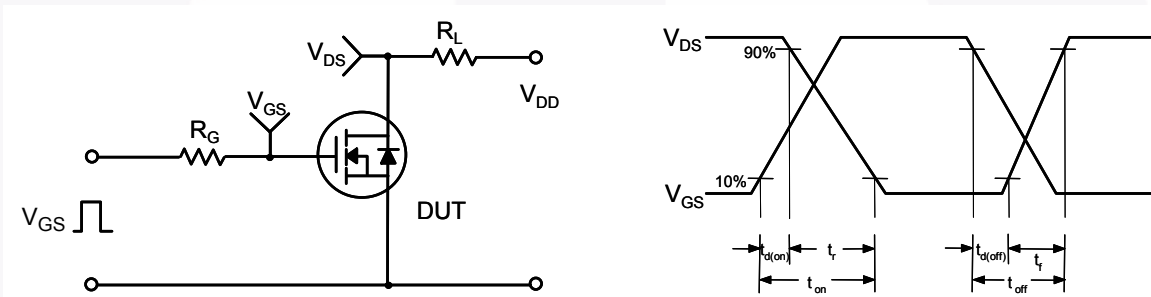


Figure 14. Resistive Switching Test Circuit & Waveforms

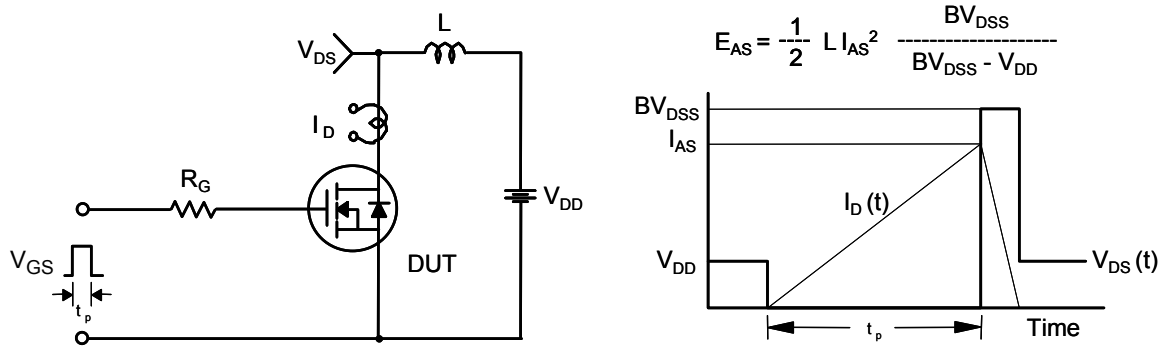
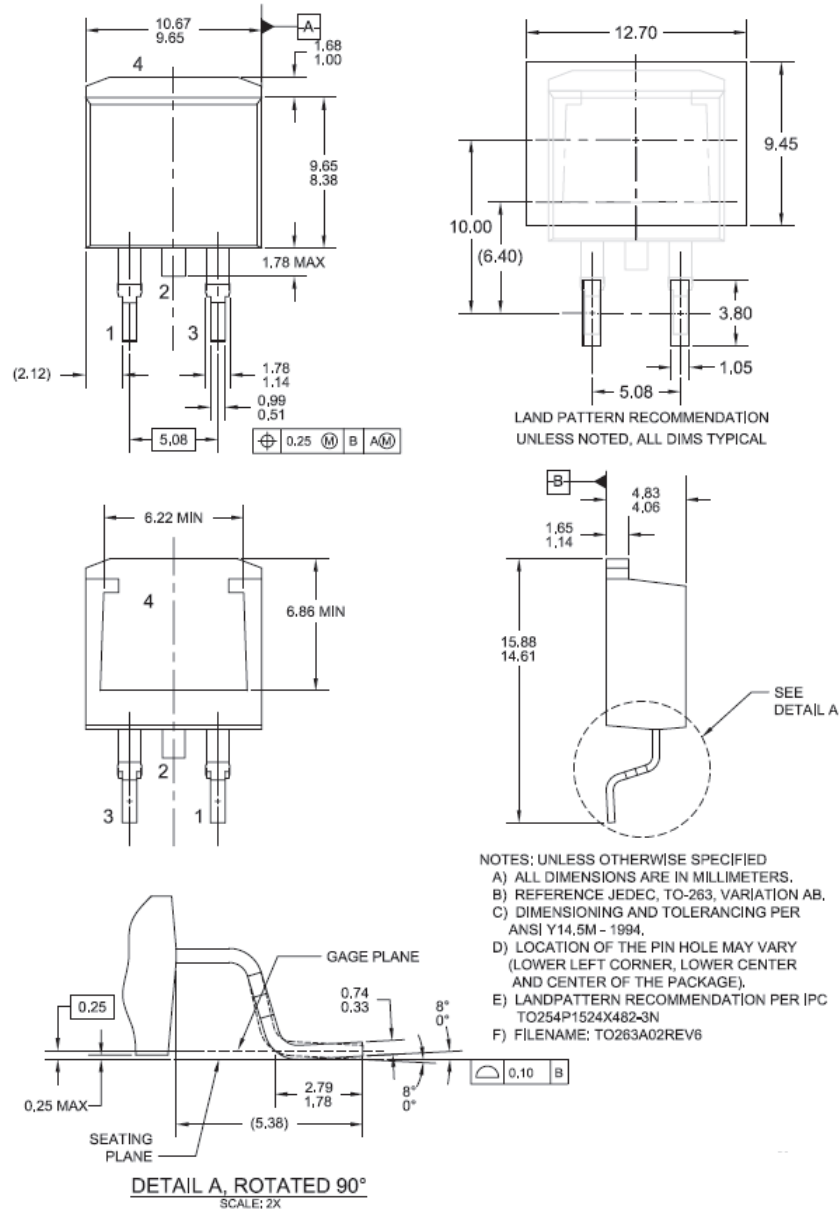


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms



Figure 16. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms

## Mechanical Dimensions



**Figure 17. TO263 (D<sup>2</sup>PAK), Molded, 2-Lead, Surface Mount**

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